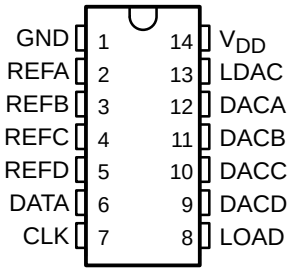
SLAS081C – NOVEMBER 1994 – REVISED FEBRUARY 1996

- **Four 8-Bit Voltage Output DACs**
- **5-V Single-Supply Operation**
- **Serial Interface**
- **High-Impedance Reference Inputs**
- **Programmable 1 or 2 Times Output Range**
- **Simultaneous-Update Facility**
- **Internal Power-On Reset**
- **Low Power Consumption**
- **Half-Buffered Output**

N OR D PACKAGE
(TOP VIEW)



applications

- **Programmable Voltage Sources**
- **Digitally-Controlled Amplifiers/Attenuators**
- **Mobile Communications**
- **Automatic Test Equipment**
- **Process Monitoring and Control**
- **Signal Synthesis**

description

The TLC5620C and TLC5620I are quadruple 8-bit voltage output digital-to-analog converters (DACs) with buffered reference inputs (high impedance). The DACs produce an output voltage that ranges between either one or two times the reference voltages and GND, and the DACs are monotonic. The device is simple to use, running from a single supply of 5 V. A power-on reset function is incorporated to ensure repeatable start-up conditions.

Digital control of the TLC5620C and TLC5620I are over a simple 3-wire serial bus that is CMOS compatible and easily interfaced to all popular microprocessor and microcontroller devices. The 11-bit command word comprises 8 bits of data, 2 DAC select bits and a range bit, the latter allowing selection between the times 1 or times 2 output range. The DAC registers are double buffered, allowing a complete set of new values to be written to the device, then all DAC outputs are updated simultaneously through control of the LDAC terminal. The digital inputs feature Schmitt triggers for high noise immunity.

The 14-terminal small-outline (D) package allows digital control of analog functions in space-critical applications. The TLC5620C is characterized for operation from 0°C to 70°C. The TLC5620I is characterized for operation from –40°C to 85°C. The TLC5620C and TLC5620I do not require external trimming.

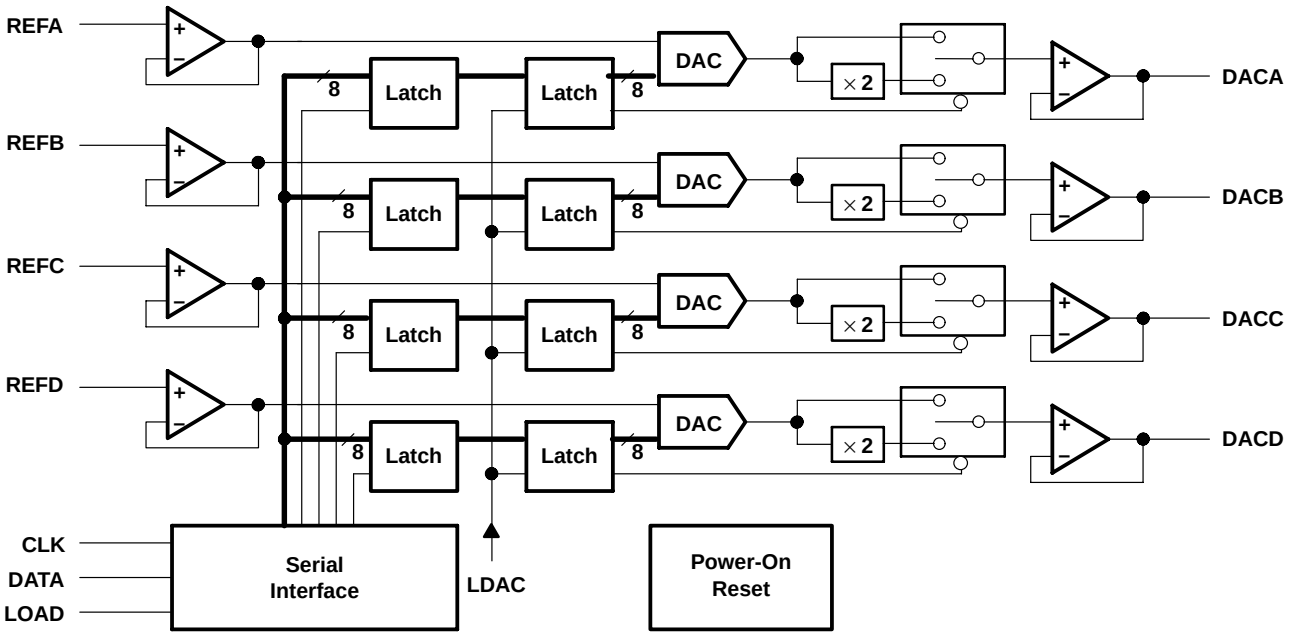
AVAILABLE OPTIONS

	PACKAGE	
T_A	SMALL OUTLINE (D)	PLASTIC DIP (N)
0°C to 70°C	TLC5620CD	TLC5620CN
–40°C to 85°C	TLC5620ID	TLC5620IN

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251–1443

functional block diagram



Terminal Functions

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
CLK	7	I	Serial interface clock, data enters on the negative edge
DACA	12	O	DAC A analog output
DACB	11	O	DAC B analog output
DACC	10	O	DAC C analog output
DACD	9	O	DAC D analog output
DATA	6	I	Serial-interface digital-data input
GND	1	I	Ground return and reference terminal
LDAC	13	I	DAC-update latch control
LOAD	8	I	Serial interface load control
REFA	2	I	Reference voltage input to DACA
REFB	3	I	Reference voltage input to DACB
REFC	4	I	Reference voltage input to DACC
REFD	5	I	Reference voltage input to DACD
V_{DD}	14	I	Positive supply voltage

detailed description

The TLC5620 is implemented using four resistor-string DACs. The core of each DAC is a single resistor with 256 taps, corresponding to the 256 possible codes listed in Table 2. One end of each resistor string is connected to the GND terminal and the other end is fed from the output of the reference input buffer. Monotonicity is maintained by use of the resistor strings. Linearity depends upon the matching of the resistor elements and upon the performance of the output buffer. Because the inputs are buffered, the DACs always present a high-impedance load to the reference source.

detailed description (continued)

Each DAC output is buffered by a configurable-gain output amplifier, which can be programmed to times 1 or times 2 gain.

On powerup, the DACs are reset to CODE 0.

Each output voltage is given by:

$$V_O(\text{DACA|B|C|D}) = \text{REF} \times \frac{\text{CODE}}{256} \times (1 + \text{RNG bit value})$$

where CODE is in the range 0 to 255 and the range (RNG) bit is 0 or 1 within the serial control word.

data interface

With LOAD high, data is clocked into the DATA terminal on each falling edge of CLK. Once all data bits have been clocked in, LOAD is pulsed low to transfer the data from the serial input register to the selected DAC as shown in Figure 1. When LDAC is low, the selected DAC output voltage is updated and LOAD goes low. When LDAC is high during serial programming, the new value is stored within the device and can be transferred to the DAC output at a later time by pulsing LDAC low as shown in Figure 2. Data is entered most significant bit (MSB) first. Data transfers using two 8-clock cycle periods are shown in Figures 3 and 4.

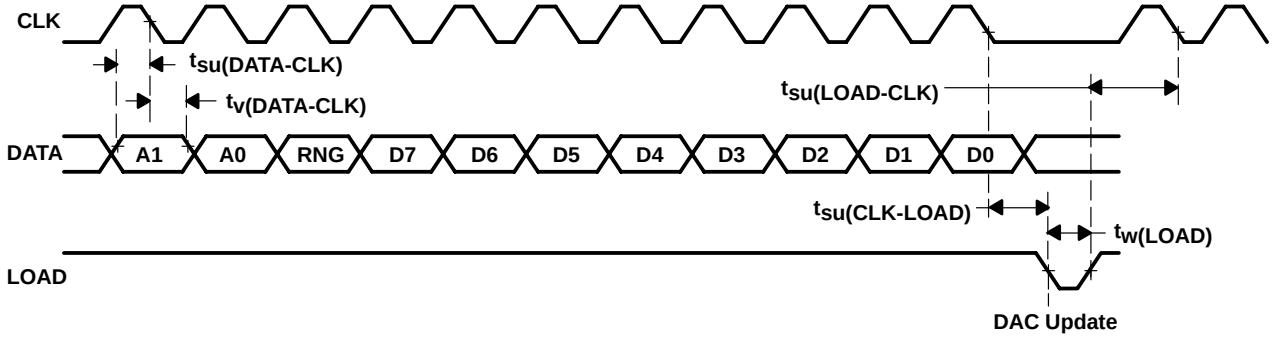


Figure 1. LOAD-Controlled Update (LDAC = Low)

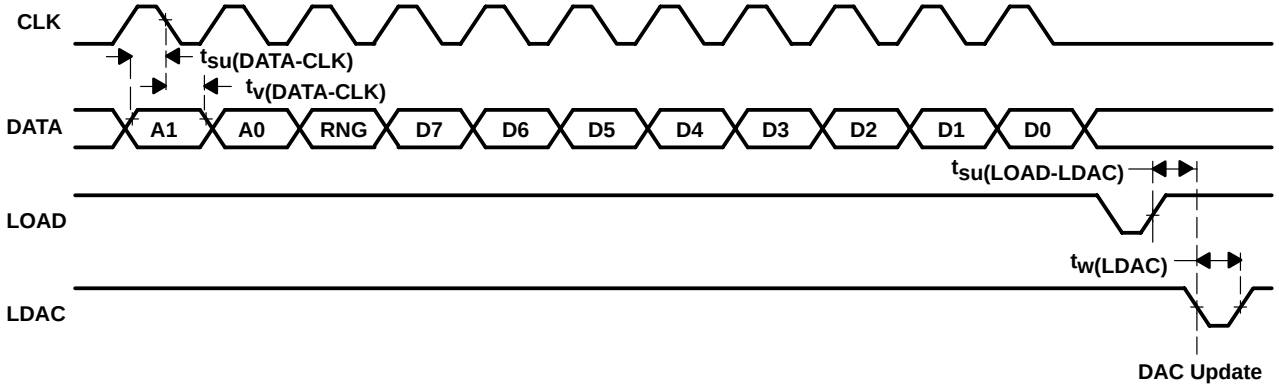


Figure 2. LDAC-Controlled Update

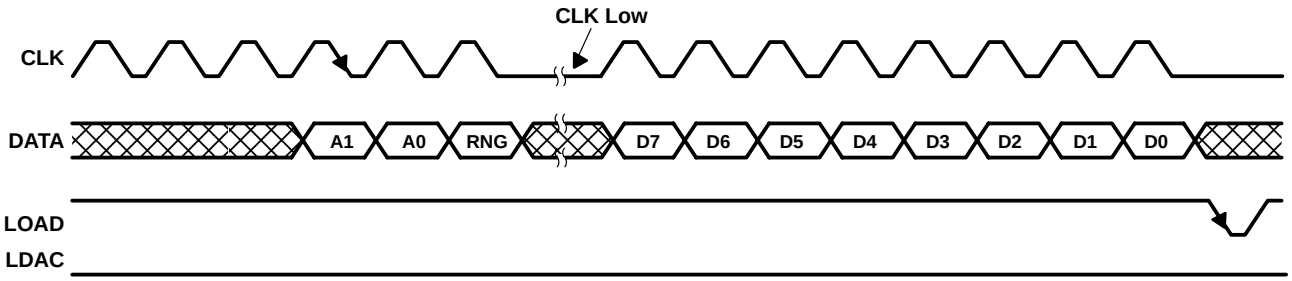


Figure 3. Load-Controlled Update Using 8-Bit Serial Word (LDAC = Low)

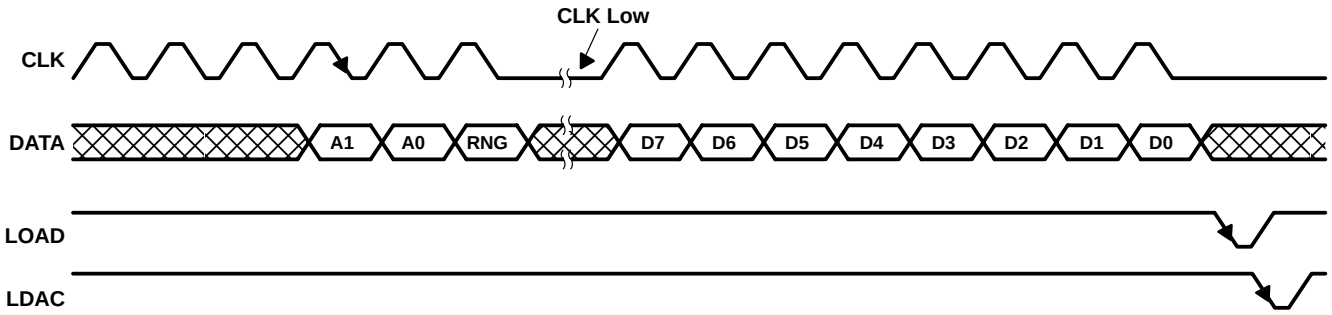


Figure 4. LDAC-Controlled Update Using 8-Bit Serial Word

data interface (continued)

Table 1 lists the A1 and A0 bits and the selection of the updated DACs. The RNG bit controls the DAC output range. When RNG = low, the output range is between the applied reference voltage and GND, and when RNG = high, the range is between twice the applied reference voltage and GND.

Table 1. Serial Input Decode

A1	A0	DAC UPDATED
0	0	DACA
0	1	DACB
1	0	DACC
1	1	DACD

Table 2. Ideal Output Transfer

D7	D6	D5	D4	D3	D2	D1	D0	OUTPUT VOLTAGE
0	0	0	0	0	0	0	0	GND
0	0	0	0	0	0	0	1	(1/256) × REF (1+RNG)
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
0	1	1	1	1	1	1	1	(127/256) × REF (1+RNG)
1	0	0	0	0	0	0	0	(128/256) × REF (1+RNG)
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
1	1	1	1	1	1	1	1	(255/256) × REF (1+RNG)

linearity, offset, and gain error using single end supplies

When an amplifier is operated from a single supply, the voltage offset can still be either positive or negative. With a positive offset, the output voltage changes on the first code change. With a negative offset the output voltage may not change with the first code depending on the magnitude of the offset voltage.

The output amplifier, with a negative voltage offset, attempts to drive the output to a negative voltage. However, because the most negative supply rail is ground, the output cannot drive to a negative voltage.

So when the output offset voltage is negative, the output voltage remains at 0 V until the input code value produces a sufficient output voltage to overcome the inherent negative offset voltage, resulting in the transfer function shown in Figure 5.

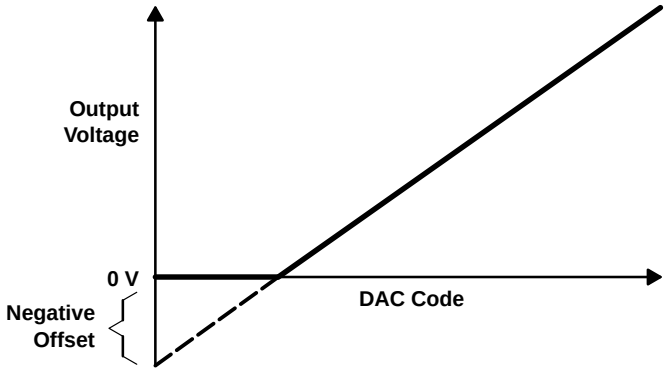


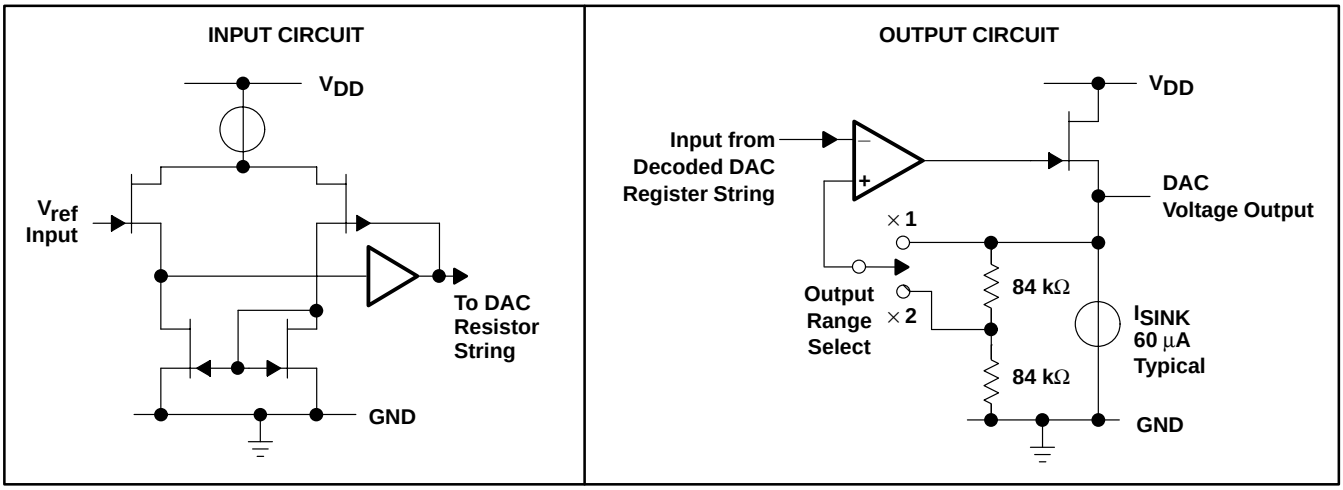
Figure 5. Effect of Negative Offset (Single Supply)

This negative offset error, not the linearity error, produces the breakpoint. The transfer function would have followed the dotted line if the output buffer could drive to a negative voltage.

For a DAC, linearity is measured between the zero-input code (all inputs are 0) and the full-scale code (all inputs are 1) after offset and full scale are adjusted out or accounted for in some way. However, single supply operation does not allow for adjustment when the offset is negative due to the breakpoint in the transfer function. So the linearity in the unipolar mode is measured between full-scale code and the lowest code which produces a positive output voltage.

The code is calculated from the maximum specification for the negative offset.

equivalent inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (V_{DD} – GND) . . . . . 7 V
Digital input voltage range . . . . . GND – 0.3 V to V_{DD} + 0.3 V
Reference input voltage range, V_{ID} . . . . . GND – 0.3 V to V_{DD} + 0.3 V
Operating free-air temperature range, T_A: TLC5620C . . . . . 0°C to 70°C
TLC5620I . . . . . –40°C to 85°C
Storage temperature range, T_{stg} . . . . . –50°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 230°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}		4.75		5.25	V
High-level digital input voltage, V_{IH}		0.8 V_{DD}			V
Low-level digital input voltage, V_{IL}				0.8	V
Reference voltage, V_{ref} [A|B|C|D]				V_{DD}–1.5	V
Analog full-scale output voltage, R_L = 10 kΩ			3.5		V
Load resistance, R_L		10			kΩ
Setup time, data input, $t_{su(DATA-CLK)}$ (see Figures 1 and 2)		50			ns
Valid time, data input valid after CLK↓, $t_{v(DATA-CLK)}$ (see Figures 1 and 2)		50			ns
Setup time, CLK eleventh falling edge to LOAD, $t_{su(CLK-LOAD)}$ (see Figure 1)		50			ns
Setup time, LOAD↑ to CLK↓, $t_{su(LOAD-CLK)}$ (see Figure 1)		50			ns
Pulse duration, LOAD, $t_{w(LOAD)}$ (see Figure 1)		250			ns
Pulse duration, LDAC, $t_{w(LDAC)}$ (see Figure 2)		250			ns
Setup time, LOAD↑ to LDAC↓, $t_{su(LOAD-LDAC)}$ (see Figure 2)		0			ns
CLK frequency				1	MHz
Operating free-air temperature, T_A	TLC5620C	0		70	°C
	TLC5620I	–40		85	°C

electrical characteristics over recommended operating free-air temperature range, V_{DD} = 5 V ± 5%, V_{ref} = 2 V, × 1 gain output range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{IH}	High-level digital input current	$V_I = V_{DD}$			±10	µA
I_{IL}	Low-level digital input current	V_I = 0 V			±10	µA
$I_{O(sink)}$	Output sink current	Each DAC output	20			µA
$I_{O(source)}$	Output source current		2			mA
C_i	Input capacitance			15		pF
	Reference input capacitance			15		
I_{DD}	Supply current	V_{DD} = 5 V			2	mA
I_{ref}	Reference input current	V_{DD} = 5 V, V_{ref} = 2 V			±10	µA
E_L	Linearity error (end point corrected)	V_{ref} = 2 V, × 2 gain (see Note 1)			±1	LSB
E_D	Differential-linearity error	V_{ref} = 2 V, × 1 gain (see Note 2)			±0.9	LSB
E_{ZS}	Zero-scale error	V_{ref} = 2 V, × 2 gain (see Note 3)	0		30	mV
	Zero-scale-error temperature coefficient	V_{ref} = 2 V, × 2 gain (see Note 4)		10		µV/°C
E_{FS}	Full-scale error	V_{ref} = 2 V, × 2 gain (see Note 5)			±60	mV
	Full-scale-error temperature coefficient	V_{ref} = 2 V, × 2 gain (see Note 6)		±25		µV/°C
PSRR	Power-supply rejection ratio	See Notes 7 and 8		0.5		mV/V

NOTES:
1. Integral nonlinearity (INL) is the maximum deviation of the output from the line between zero and full scale (excluding the effects of zero code and full-scale errors).
2. Differential nonlinearity (DNL) is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.
3. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
4. Zero-scale-error temperature coefficient is given by: $ZSETC = [ZSE(T_{max}) – ZSE(T_{min})]/V_{ref} \times 10^6/(T_{max} – T_{min})$.
5. Full-scale error is the deviation from the ideal full-scale output (V_{ref} – 1 LSB) with an output load of 10 kΩ.
6. Full-scale-temperature coefficient is given by: $FSETC = [FSE(T_{max}) – FSE(T_{min})]/V_{ref} \times 10^6/(T_{max} – T_{min})$.
7. Zero-scale-error rejection ratio (ZSE RR) is measured by varying the V_{DD} from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the zero-code output voltage.
8. Full-scale-error rejection ratio (FSE RR) is measured by varying the V_{DD} from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the full-scale output voltage.

operating characteristics over recommended operating free-air temperature range, V_{DD} = 5 V ± 5%, V_{ref} = 2 V, × 1 gain output range (unless otherwise noted)

	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output slew rate	C_L = 100 pF, R_L = 10 kΩ		1		V/µs
Output settling time	To 0.5 LSB, C_L = 100 pF, R_L = 10 kΩ, See Note 9		10		µs
Large-signal bandwidth	Measured at –3 dB point		100		kHz
Digital crosstalk	CLK = 1-MHz square wave measured at DACA-DACD		–50		dB
Reference feedthrough	See Note 10		–60		dB
Channel-to-channel isolation	See Note 11		–60		dB
Reference input bandwidth	See Note 12		100		kHz

NOTES:
9. Settling time is the time for the output signal to remain within ±0.5 LSB of the final measured value for a digital input code change of 00 hex to FF hex or FF hex to 00 hex. For TLC5620C: V_{DD} = 5 V, V_{ref} = 2 V and range = ×2. For TLC5620I: V_{DD} = 3 V, V_{ref} = 1.25 V and range ×2.
10. Reference feedthrough is measured at any DAC output with an input code = 00 hex with a V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz.
11. Channel-to-channel isolation is measured by setting the input code of one DAC to FF hex and the code of all other DACs to 00 hex with V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz.
12. Reference bandwidth is the –3 dB bandwidth with an input at V_{ref} = 1.25 V dc + 2 V_{pp}, with a full-scale digital-input code.

PARAMETER MEASUREMENT INFORMATION

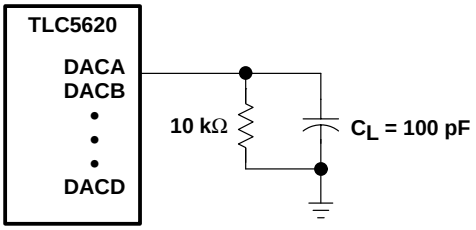


Figure 6. Slewing Settling Time and Linearity Measurements

TYPICAL CHARACTERISTICS

POSITIVE RISE AND SETTLING TIME

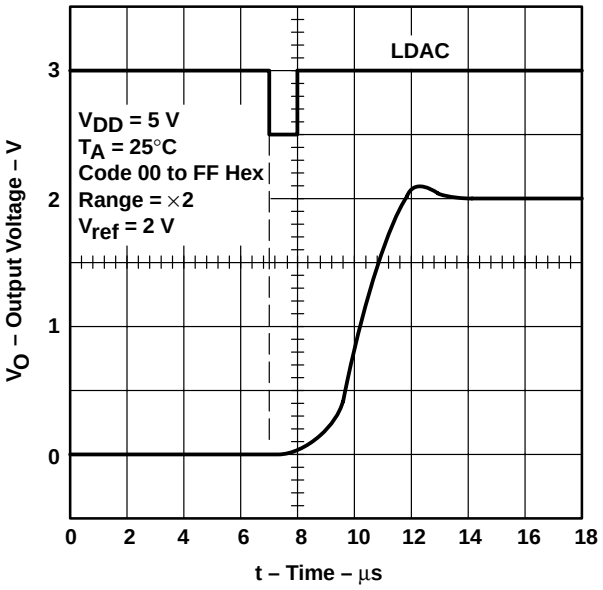


Figure 7

NEGATIVE FALL AND SETTLING TIME

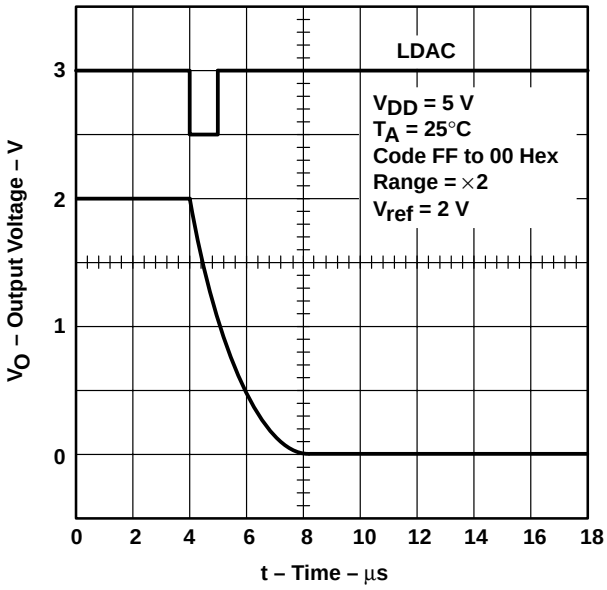


Figure 8

TYPICAL CHARACTERISTICS

DAC OUTPUT VOLTAGE vs LOAD

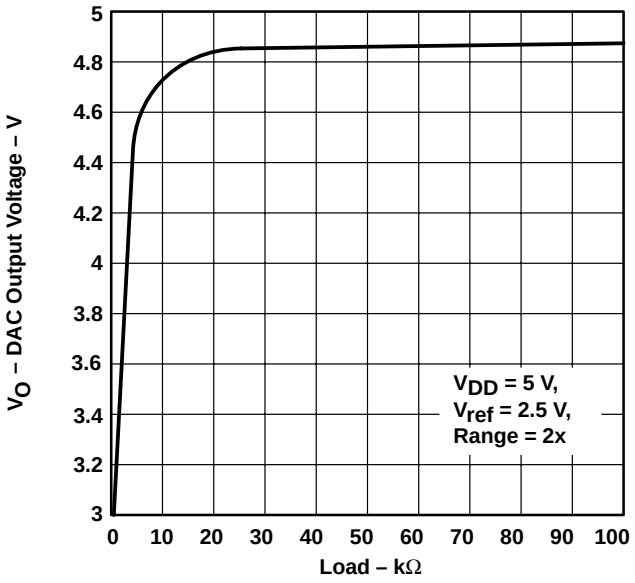


Figure 9

DAC OUTPUT VOLTAGE vs LOAD

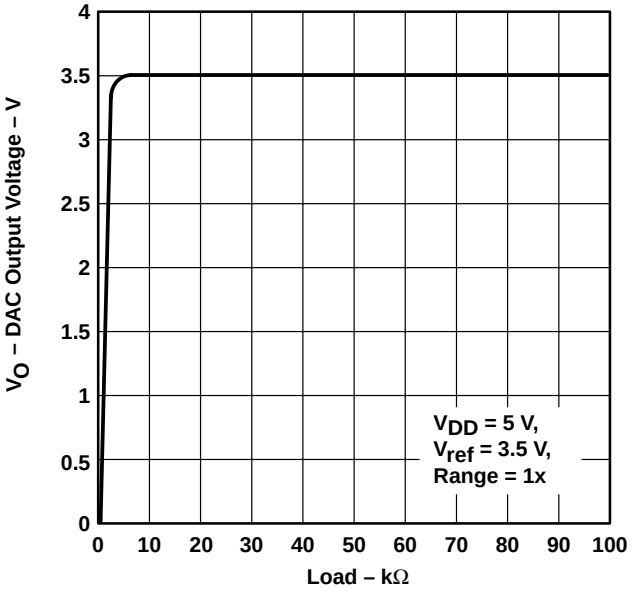


Figure 10

OUTPUT SOURCE CURRENT vs OUTPUT VOLTAGE

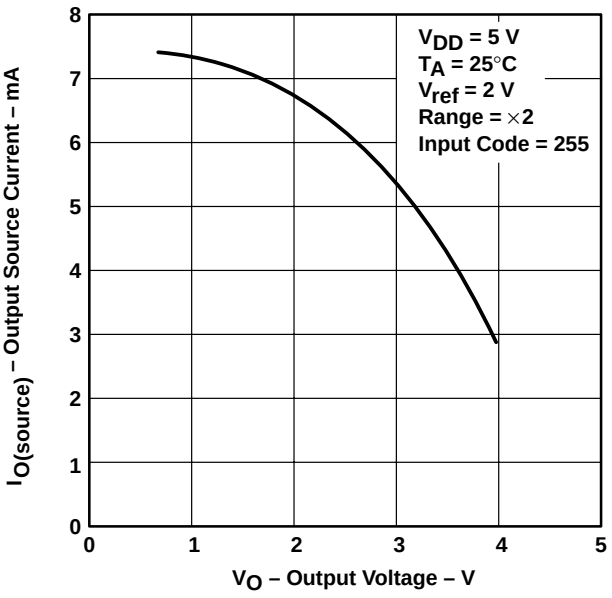


Figure 11

SUPPLY CURRENT vs TEMPERATURE

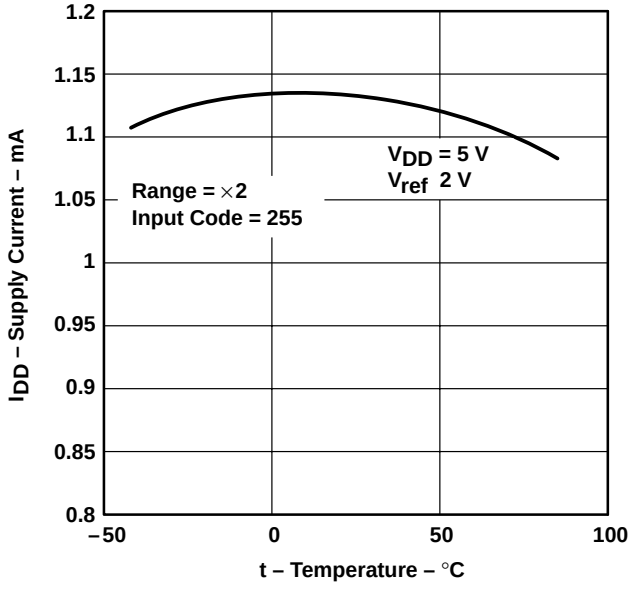


Figure 12

TYPICAL CHARACTERISTICS

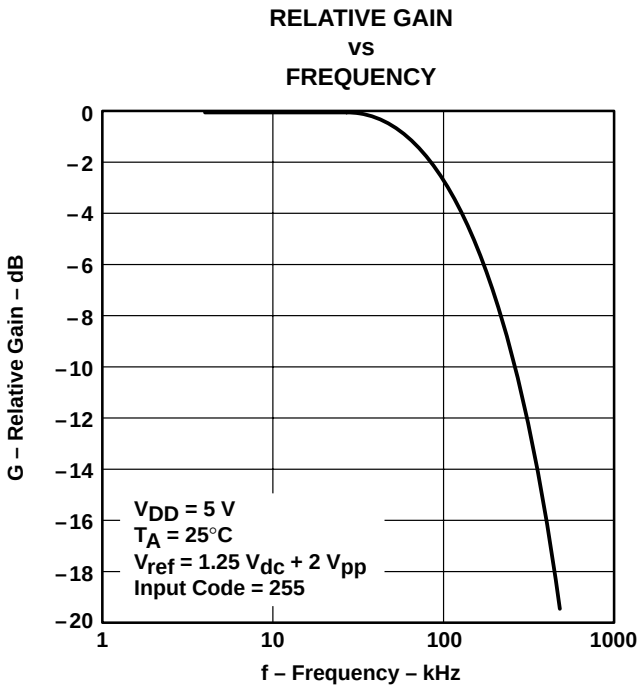


Figure 13

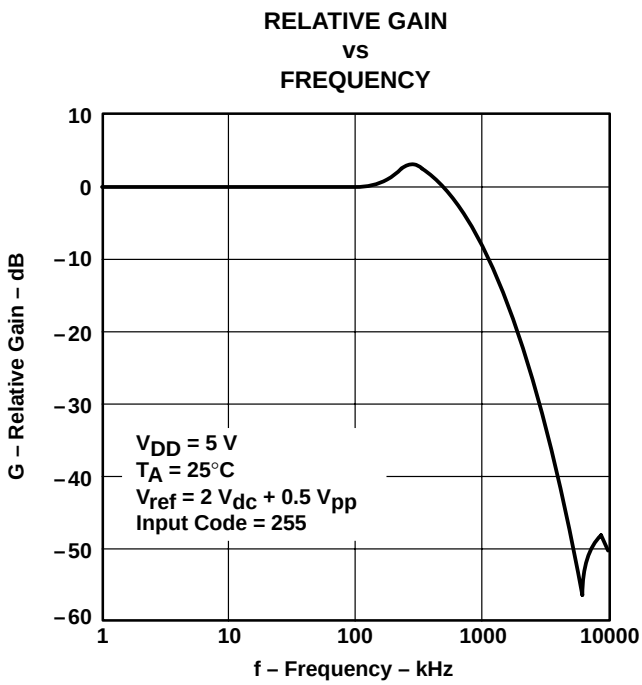
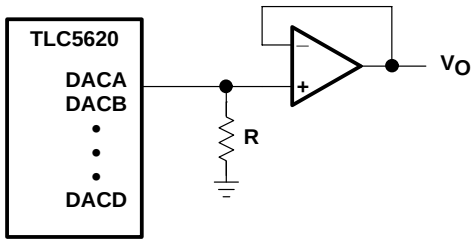


Figure 14

APPLICATION INFORMATION



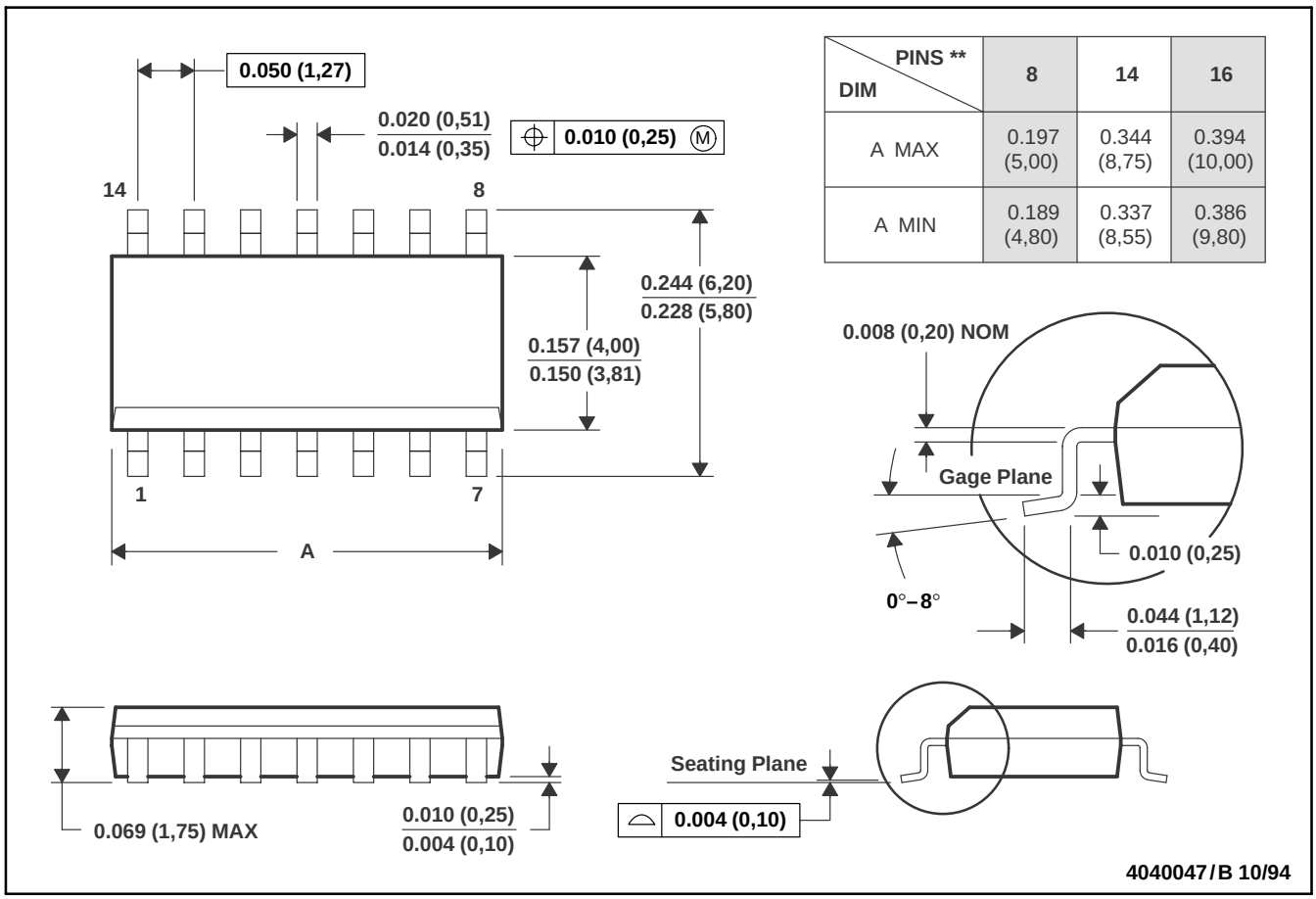
NOTE A: Resistor R ≥ 10 kΩ

Figure 15. Output Buffering Scheme

MECHANICAL DATA

D (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PIN SHOWN



DIM \ PINS **	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)

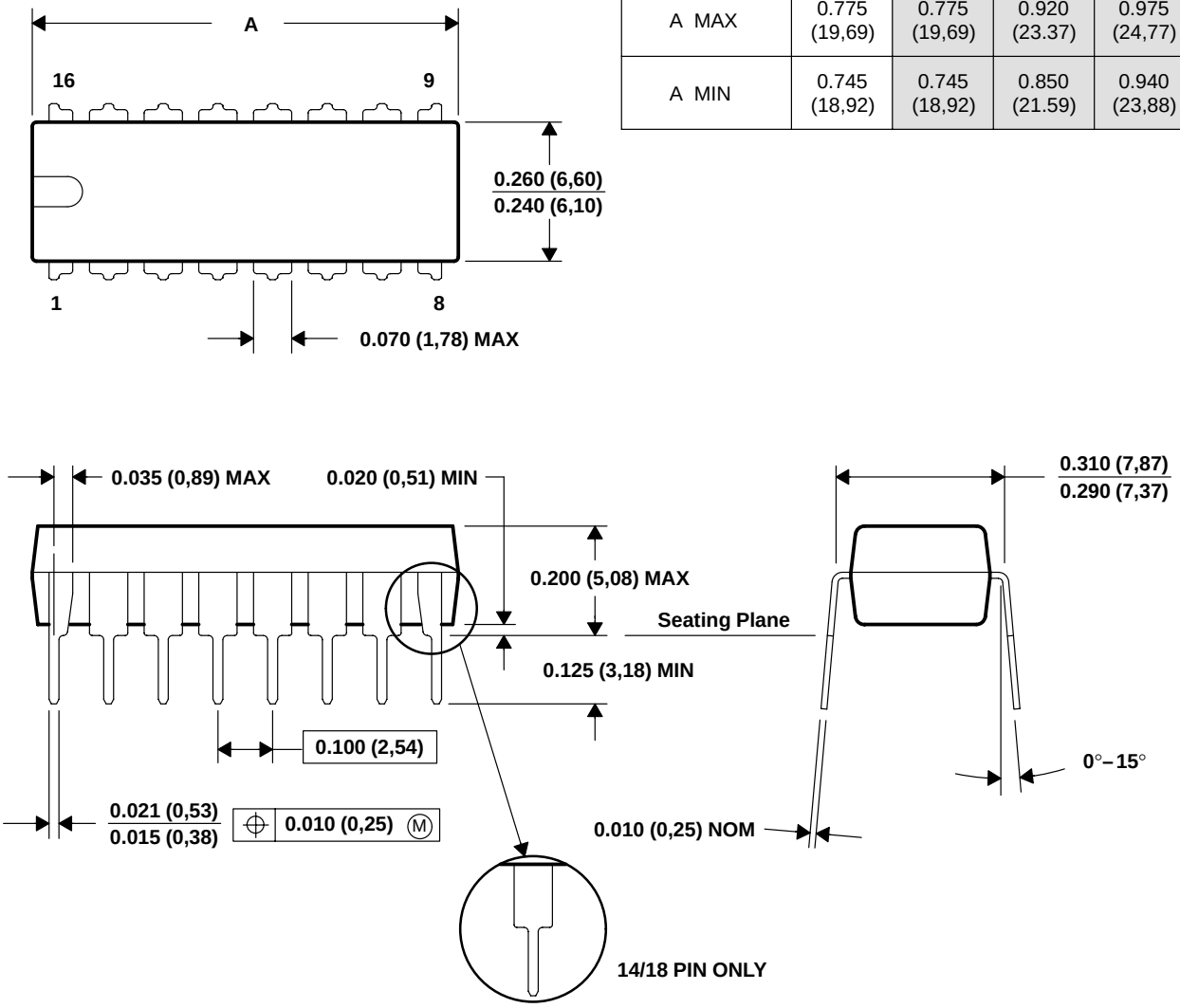
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Four center pins are connected to die mount pad.
E. Falls within JEDEC MS-012

MECHANICAL DATA

N (R-PDIP-T)** **PLASTIC DUAL-IN-LINE PACKAGE**

16 PIN SHOWN

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23.37)	0.975 (24,77)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21.59)	0.940 (23,88)



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001 (20-pin package is shorter than MS-001)

IMPORTANT NOTICE

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.